(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
14 July 2005 (14.07.2005)

PCT

(10) International Publication Number
WO 2005/064408 A3

(51) International Patent Classification[7]: G03F 7/20

(21) International Application Number:
PCT/IB2004/052723

(22) International Filing Date:
9 December 2004 (09.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
03104955.4 23 December 2003 (23.12.2003) EP

(71) Applicant *(for all designated States except US)*: **KONINKLIJKE PHILIPS ELECTRONICS N.V.** [NL/NL]; Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **SCHEUCHER, Heimo** [AT/AT]; Triester Strasse 64, A-1101 Vienna (AT). **PFEILER, Günther** [AT/AT]; Triester Strasse 64, A-1101 Vienna (AT). **WENTING, Rik** [NL/NL]; Triester Strasse 64, A-1101 Vienna (AT).

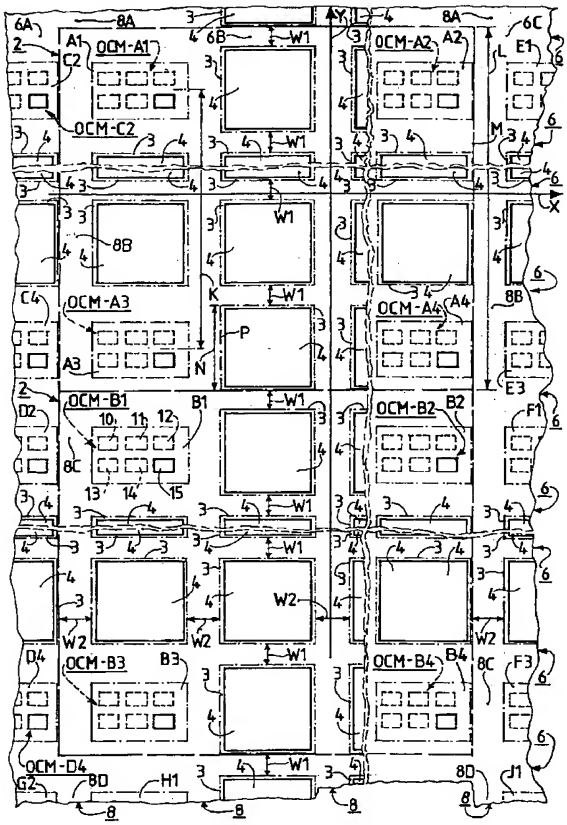
(74) Agents: **RÖGGLA, Harald** et al.; Philips Intellectual Property & Standards, Triester Strasse 64, A-1101 Vienna (AT).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

[Continued on next page]

(54) Title: WAFER WITH OPTICAL CONTROL MODULES IN EXPOSURE FIELDS



(57) Abstract: In a wafer (1) with a number of exposure fields (2), each of which exposure fields (2) comprising a number of lattice fields (3) with an IC (4) located therein, two groups (5, 7) of dicing paths (6, 8) are provided and four control module fields (A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, El, E3, Fl, F3, G2, Hi, J1) are assigned to each exposure field (2), each of which control module fields (A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, El, E3, Fl, F3, G2, H1, J1) contains at least one optical control module (OCM-Al, OCMA2, OCM-A3, OCM-A4, OCM-B1, OCM-B2, OCM-B3, OCM-B4, OCM-C2, OCM-D4) and lies within the exposure field (2) in question and is provided in place of at least one lattice field (3) and is arranged at a mutual minimum distance (K).

WO 2005/064408 A3